

(0.635 mm) .025"

MIT-038-01-F-D

MIT-019-01-F-D

MIT-057-01-L-D

MIT SERIES

MIXED TECHNOLOGY HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MIT

Insulator Material:

Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Operating Temp Range:

-55 °C to +125 °C

Voltage Rating:

275 VAC/389 VDC

Max Cycles:

100

RoHS Compliant:

Yes

Board Mates:
MIS

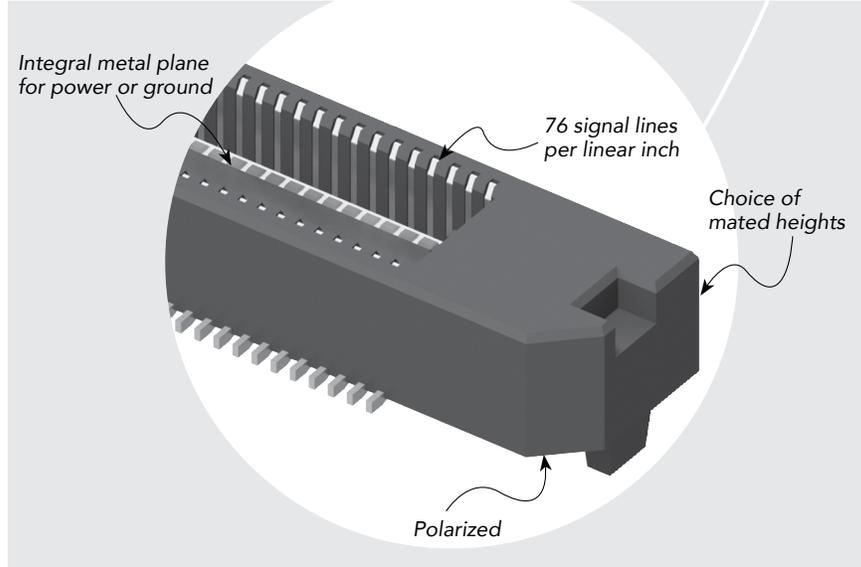
Standoffs:
SO

Integral metal plane for power or ground

76 signal lines per linear inch

Choice of mated heights

Polarized



PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (019-057)

Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

ALSO AVAILABLE Contact Samtec

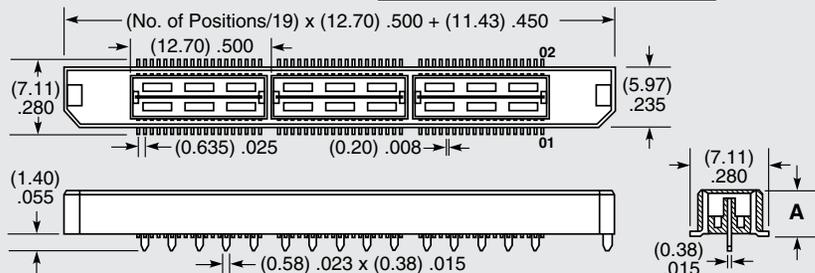
- 11 mm, 16 mm, 18.75 mm and 22 mm stack height
- 30 μ" (0.76 μm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 76, 95, 114 and 133 positions per row

MIT	POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	OPTION	PACKAGING
	-019, -038, -057 (38 total positions per bank)	Specify LEAD STYLE FROM chart	<p>-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails</p> <p>-L = 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane, Matte Tin on tails</p> <p>-C* = Electro-Polished Selective 50 μ" (1.27 μm) min Au over 150 μ" (3.81 μm) Ni on Signal Pins in contact area, 10 μ" (0.25 μm) min Au over 50 μ" (1.27 μm) Ni on Ground Plane in contact area, Matte Tin over 50 μ" (1.27 μm) min Ni on all solder tails</p>		<p>-K = (7.00 mm) .275" DIA Polyimide film Pick & Place Pad</p>	<p>Leave blank for tray packaging</p> <p>-TR = Tape & Reel</p> <p>-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)</p>

*Note:
-C Plating passes 10 year MFG testing

MATED HEIGHT*		
MIS LEAD STYLE	MIT LEAD STYLE	
-01	-01	-02
	(5.00) .197	(8.00) .315

*Processing conditions will affect mated height. See SO Series for board space tolerances.



LEAD STYLE	A
-01	(4.27) .168
-02	(7.26) .286

Note:
Some lengths, styles and options are non-standard, non-returnable.

Note: Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press-fit) for added retention to PCB.